

SBR10100CTB SBR10200CTB SBR1040CTB SBR10U200CTB SBR20A200CTB SBR30A100CTB SBR30A45CTB SBR30A60CTB SBR40U200CTB SBR40U300CTB
SBR660CTL

Part Number: **SBR D2PAK**
Weight (mg): 1488.048

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si, Doped	7440-21-3	100.00%	0.91	13.5	1000000	9072
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.42	6.3	925000	3916
		Sn	7440-31-5	5.00%			50000	212
		Ag	7440-22-4	2.50%			25000	106
Leadframe & Clip	Copper Alloy	Copper	7440-50-8	92.40%	52.13	775.7672	924000	481711
		Fe	7439-89-6	0.10%			1000	521
		Phosphorus	7723-14-0	0.03%			300	156
	Nickel	7440-02-0	0.03%	300			156	
	Die pad plating	Ag	7740-22-4	100.00%	0.02	0.2328	1000000	156
Encapsulation	Epoxy	Silica Fused	60676-86-0	73.00%	43.35	645	730000	316421
		Epoxy Resin	29690-82-2	12.00%			120000	52014
		Phenolic Resin	9003-35-4	7.00%			70000	30342
		Misc	-----	4.00%			40000	17338
		Flame Retardant	-----	2.00%			20000	8669
		Brominated Resin	N/A	1.50%			15000	6502
		Carbon Black	1333-86-4	0.50%			5000	2167
Bonding Wire	15 mil Wire	Al	7429-90-5	100.00%	0.82	12.248	1000000	8231
Lead Plating Finish	Tin Solder	Sn (>99.5%)	7440-31-5	100.00%	2.35	35	1000000	23521
				Total	100.00	1488.05		961213

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentaoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder applied